

Atty. Dkt. No. 039153-0472 (G1177)

Amendments to the Specification:

Please amend the specification as follows:

Please replace paragraph number [0001] with the following rewritten paragraph:

[0001] This application is related to U.S. Patent Application No. \_\_\_\_\_  
09/994,440, Attorney Docket No. 39153/474 (G1179), entitled METHOD OF INSERTING  
ALLOY ELEMENTS TO REDUCE COPPER DIFFUSION AND BULK DIFFUSION; U.S.  
Patent Application No. \_\_\_\_\_, Attorney Docket No. 39153/519 (G1224), entitled  
USE OF MULTIPLE ELEMENTS TO FORM A ROBUST, ELECTROMIGRATION  
RESISTANT COPPER INTERCONNECT, U.S. Patent Application No. \_\_\_\_\_  
09/994,395, Attorney Docket No. 39153/457 (G1162), entitled METHOD OF USING  
TERNARY COPPER ALLOY TO OBTAIN A LOW RESISTANCE AND LARGE GRAIN  
SIZE INTERCONNECT; U.S. Patent Application No. \_\_\_\_\_ 09/994,358, Attorney  
Docket No. 39153/455 (G1160), entitled METHOD OF IMPLANTATION AFTER COPPER  
SEED DEPOSITION; and U.S. Patent Application No. \_\_\_\_\_ 10/123,751, Attorney  
Docket No. 39153/529 (G1234), entitled USE OF ULTR-LOW ENERGY ION  
IMPLANTATION (ULEI) TO FORM ALLOY LAYERS IN COPPER which are all  
assigned to the same assignee as this application.